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03/15/02

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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10099641	FILING DATE 03/15/2002	CLASS 438	SUBCLASS 757	GAU 2829	EXAMINER
**APPLICANTS: Catabay Wilbur; Schinella Richard;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/426,056 10/22/1999 PAT 6,391,795					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/> RESCIND <input type="checkbox"/>					
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 99-102/1D	
TITLE : Low k dielectric composite layer for integrated circuit structure which provides void-free low k dielectric material between metal lines while mitigating via poisoning					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner		CLAIMS ALLOWED	
				Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING		
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner		
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